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焊接指导（2）

Guideline for Soldering (2)

ضي U ą ˇ ضي Ь G 30Ņ Ð Й 3 № ˇ Ь G 50Ņ Ð Й

30 Â

ą ï ŕ ³ ╕ ╠˘ ѽ ą ╕ Ь Ψ LED ė № Н Â

Ӟ ˇ ѿ ѡ Ь 300Wˇ Ղ ↕˜ LED Н Â

ĺ r ' ѽ Ð Ղ Ψ LED Н Â

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30Ņ for 3 minutes or 50Ņ for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pretest should be done to confirm whether any damage to LEDs will occur.

✱ **注意：** ѿ ∧ ↕ Ь G PCB

使用注意事项（2）

Precautions (2)

设计建议